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Enhanced Light Emission of Micro LEDs Using Graphene-Connected Micropillar Structures and Ag/SiO₂ Nanoparticles

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shows an improvement of 44% in external quantum efficiency (EQE) and 45% in wall plug efficiency (WPE) at a current density of 1000 A/cm². This study demonstrates the significant application potential of LSPR and micropillar structures in μ LED technology. **KEYWORDS:** *localized surface plasmon resonance, graphene, micropillar, micro-LED*

INTRODUCTION

In the preparation method of full-color micro-LED (μ LED) display arrays, blue μ LEDs can serve as one of the three primary colors and integrate with green and red μ LEDs to form a full-color display array.^{1–3} Alternatively, blue μ LEDs can be used as excitation light sources to excite green and red quantum dots to create a full-color display array.^{4–10} Therefore, blue μ LEDs are the core components in new display technologies, and their performance significantly affects the overall display effect of μ LED full-color display arrays. However, due to material properties and sidewall defects, there is still significant room for improvement in the luminous efficiency and external quantum efficiency (EQE) of μ LEDs.^{11–14}

For GaN-based μ LEDs, the significant difference between the refractive index of GaN (~2.5) and that of air (~1) results in a small light escape angle, limiting the light extraction efficiency (LEE).^{15,16} Furthermore, in InGaN/GaN quantum wells (QW), the quantum-confined Stark effect (QCSE) primarily caused by piezoelectric polarization leads to a decrease in radiative recombination within the QWs.¹⁷ In addition to material constraints, the impact of sidewall defects in μ LEDs is also significant. This is because the sidewall area constitutes a large proportion of the emitting surface, and sidewall defects introduced during etching substantially increase the probability of nonradiative recombination in $\mu \text{LEDs},$ limiting the improvement of internal quantum efficiency (IQE).^{18-21}

Localized surface plasmon resonance (LSPR) has been widely demonstrated to enhance the radiative recombination efficiency of LEDs.^{22–24} However, LSPR strongly depends on the distance between the localized surface plasmon (LSP) and the QW, and significant coupling occurs only when this distance is less than 100 nm.^{25,26} Micropillar (MP) structures can enable direct contact between the LSP and the QW with minimal sacrifice of the active region area, overcoming the distance limitation for LSP-QW coupling efficiency.²⁷ Moreover, MP structures can relieve stress, suppress QCSE, and provide more escape paths for photons, especially in GaNbased LEDs.^{28,29}

In blue LEDs, Ag nanoparticles (NPs) are commonly used as LSPs. However, direct contact between the QW and Ag NPs can lead to electron tunneling between the QW and Ag NPs, resulting in energy annihilation. The same electron tunneling can occur between Ag NPs when they are in contact with each

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Figure 1. (a) Epitaxial structure; (b) Etching the light-emitting mesa; (c) Arranging SiO_2 nanospheres; (d). Etching micropillars; (e) Sputtering metal electrodes; (f) Spin-coating Ag NPs and Ag/SiO₂ NPs; (g) Transferring graphene; (h) Final device schematic.

other.^{30–34} If there is an insulating layer on the surface of Ag NPs, the probability of such electron tunneling can be significantly reduced.^{35,36} This insulating layer can also prevent the decrease in LSP coupling efficiency caused by the oxidation of Ag NPs.

To address the issues mentioned above, we etched micropillar arrays on the surface of µLEDs down to the N-GaN layer, exposing more QWs to the air. On this basis, Ag NPs with a SiO₂ insulating layer were filled into the gaps of the micropillar arrays, allowing direct contact between Ag/SiO₂ NPs and QWs. This approach utilizes LSPR to enhance the radiative recombination efficiency of carriers in the QWs. With the addition of Ag NPs wrapped in a SiO₂ insulating layer, the photoluminescence (PL) intensity of the micropillar arrays increased by 57%, compared to 19% when Ag NPs without the SiO₂ insulating layer were used. Considering issues related to current spreading and emission uniformity after etching the micropillars, we transferred a mono layer of graphene onto the surface of the micropillars as a transparent conductive layer. This layer connects the isolated micropillars, resulting in the fabrication of a micropillar- μ LED (MP- μ LED) that utilizes LSPR to enhance emission. This device demonstrated excellent optoelectronic performance. Compared to plane μ LEDs of the same size, the MP- μ LEDs with Ag/SiO₂ NPs exhibited a 45% increase in wall plug efficiency (WPE) and a 44% increase in EQE at a current density of 1000 A/cm^2 .

MATERIALS AND METHODS

Figure 1 shows the fabrication method of LSPR enhanced MP- μ LED. In this experiment, commercially available sapphire

substrate GaN-based blue LED epitaxial wafers were used. To ensure good ohmic contact between the metal electrode and the P-GaN and to enhance current spreading, a 110 nm layer of indium tin oxide (ITO) was sputtered on the surface of the P-GaN as a current spreading layer. After this, inductively coupled plasma reactive ion etching (ICP-RIE) was used to etch the light-emitting mesa with dimensions of 50 μ m \times 50 μ m. Subsequently, a dip-coating machine was used to cover the surface with 800 nm diameter SiO₂ nanospheres as an etching hard mask, and ICP-RIE was used to etch the micropillars. After removing the nanospheres, the sample was subjected to a KOH solution at 85 °C to repair sidewall damage incurred during the etching process. Subsequently, 300 nm of SiO₂ was deposited using inductively coupled plasma chemical vapor deposition (ICPCVD) as a sidewall passivation layer and electrode isolation layer. Then, 15/300 nm of Ti/Au was sputtered as the metal electrode. To investigate whether the presence of an insulating layer on the surface of Ag NPs has a significant impact on the performance of MP- μ LEDs, Ag NPs and Ag/SiO₂ NPs were respectively spin-coated into the gaps of the micropillars to form control groups. After spin coating, the tops of the micropillars were gently wiped with a cotton swab to keep the micropillar surfaces clean. Finally, a monolayer layer of graphene was transferred as a transparent electrode to connect the micropillars, ensuring excellent emission uniformity and current spreading.

RESULTS

In this experiment, Ag NPs serve as the LSP, and the presence or absence of a SiO_2 insulating layer on the surface of the Ag



Figure 2. (a) QW-LSP coupling schematic; (b) Energy band structure when QW is in contact with Ag; (c) Energy band structure when QW is in contact with Ag/SiO₂.



Figure 3. (a). TEM image of Ag NPs; (b) TEM image of Ag/SiO_2 NPs and enlarged view of the area marked with a red dashed line; (c) Structural schematic, TEM image, and corresponding EDS spectrum of a single Ag/SiO_2 NP; (d) Absorption spectra of Ag NPs and Ag/SiO_2 NPs; (e) Micropillar morphology before spin-coating NPs; (f) Micropillar morphology after spin-coating Ag/SiO₂ NPs and the corresponding EDS spectrum.

NPs is the variable under study. In the Supporting Information, we conducted experimental tests and simulation on Ag/SiO_2 with different thicknesses of SiO_2 , ultimately setting the thickness of SiO_2 in this experiment at 5 nm.

Explanation of LSPR Mechanism and Charge Transfer between the QW and Ag. As shown in Figure 2a, the coupling mechanism of Ag NPs and QWs is based on LSPR. When the absorption wavelength of Ag NPs matches the



Figure 4. (a) Simulation results of Ag NPs with QWs; (b) Simulation results of Ag/SiO₂ NPs with QWs; (c) PL spectra of the three types of micropillars structures; (d) TRPL spectra of plane structure and micropillar structures.

emission wavelength of the QWs, LSPR occurs, enhancing the electromagnetic field near the QWs. This increases the radiative recombination efficiency of carriers in the QWs, thus enhancing the light output.

When the QW is in direct contact with or in very close proximity to Ag, another accompanying mechanism may occur; there can be charge transfer between the two. Figure 2b and c, respectively, illustrate the energy band diagrams when the QWs are in contact with Ag and Ag/SiO_2 . The work function of QWs ranges from 4.5 to 5.5 eV, while that of Ag ranges from 4.26 to 4.74 eV. Electrons in the Ag can be excited to energy states above the conduction band edge of the QWs by surface plasmon waves. These excited electrons can then drop into the conduction band and defect levels of the QWs, increasing bandgap and defect emissions.³⁰ When the work function of the QWs is less than that of Ag, the energy band on the QW side bends upward, preventing electrons within the QWs from moving into the Ag and thus avoiding energy annihilation. However, when the work function of the QWs is greater than that of Ag, as shown in Figure 2b, The downward bending of the energy band on the QW side causes electrons to tunnel into the Ag, leading to energy annihilation. Adding an insulating layer between the Ag and QWs, as shown in Figure 2c, prevents the direct transfer of electrons from the QWs to the Ag, thus avoiding the energy annihilation caused by electron tunneling between the QWs and Ag. Based on this concept, our experiment investigated the differences in the effects of Ag/SiO₂ NPs and Ag NPs in enhancing the lightemission of MP-µLEDs.

NPs and MPs. We prepared Ag NPs without an insulating layer and Ag/SiO₂ NPs with SiO₂ insulating layers of 5 and 15 nm thicknesses, respectively. The detailed preparation process is provided in the supple information. Since the coupling efficiency of LSP with QW is highly dependent on their distance, we hypothesized that different thicknesses of SiO₂ would affect the experimental results. Therefore, we performed finite element analysis on the coupling of these three types of Ag NPs with QWs. The simulation results showed that the coupling was most effective when the SiO₂ thickness was 5 nm. To verify this simulation result, we incorporated these three types of Ag NPs into MP-µLEDs and measured their optical performance. We found that the devices with 5 nm SiO₂ exhibited the highest light output power and EQE, consistent with the simulation results. Therefore, we chose Ag/SiO₂ NPs with a 5 nm SiO₂ thickness for this study. The model construction and optical properties from the finite element analysis are presented in the Supporting Information.

Figure 3a and b are transmission electron microscope (TEM) images of Ag NPs without and with SiO_2 coating, respectively, showing relatively uniform spherical particles. Through the enlarged image at the red dashed line position, it can be seen that there is a layer of SiO_2 separating the NPs. The structural schematic and energy dispersive spectrometer (EDS) spectra of Ag/SiO₂ NPs are shown in Figure 3c, clearly indicating that the Ag/SiO₂ NPs are uniformly coated with SiO_2 . This coating forms an insulating layer between Ag and QWs, preventing electron tunneling. As shown in Figure 3d, we measured the visible light absorption of Ag NPs and Ag/SiO₂ NPs, and both absorption spectra peaks matched the



Figure 5. (a) Overall morphology of MP- μ LED and the emitting surface morphology; (b, c) Surface morphology of micropillars before and after transferring graphene; (d) Transmittance of the graphene used in the experiment at different wavelengths; (e) Raman spectra before and after transferring graphene; (f) IV characteristics and light output power of MP- μ LED before and after transferring graphene; (g) EL spectra of MP- μ LED at 20 mA before and after transferring graphene.

emission spectrum range of the μ LEDs prepared in this experiment. This match is one of the prerequisites for LSP resonance between Ag NPs and QWs. Another prerequisite is that the distance between Ag NPs and QWs should be less than 100 nm, which the micropillar structure can achieve. Figure 3e,f show the surface morphology of the etched micropillars and the surface morphology after spin-coating Ag/ SiO₂ NPs, along with their EDS spectrum. It is evident that enough nanoparticles can be accommodated in the gaps of the micropillars. Therefore, with the help of the micropillar structure, the nanoparticles can be in close contact with the QWs, ensuring sufficient LSP coupling.

Figure 4a shows the finite element analysis structure of the coupling between Ag NPs and Ag/SiO₂ NPs with QWs. The detailed model construction is provided in the Supporting Information. In the absence of a SiO₂ insulating layer, the strong electric field is only distributed near the dipole positions and does not propagate throughout all LSPs in the system, which is likely caused by energy leakage due to electron tunneling during the direct contact between Ag-QW and Ag-Ag. This means that the energy generated by LSPR is only concentrated near the point dipole and cannot be effectively transferred throughout the structure. In contrast, Figure 4b shows a much more pronounced coupling effect between Ag/ SiO₂ NPs and QWs. Each NP exhibits a strong LSPR, not just localized near the point dipole, indicating that the LSPR energy can be effectively transferred rather than being annihilated through electron tunneling.

The photoluminescence (PL) spectra of micropillars without any NPs, and those filled with Ag NPs and Ag/SiO₂ NPs, are shown in Figure 4c. The enhancement of the micropillar PL is more significant with the SiO₂-insulated Ag/SiO₂ NPs, increasing by 57%, whereas the enhancement is 19% without the SiO₂ insulating layer. Figure 4d shows the time-resolved photoluminescence (TRPL) spectra of the three samples and a plane structure. After etching the micropillars, the PL decay lifetime decreases due to improved epitaxial stress and reduced QCSE effect, leading to faster recombination of carriers in the QWs. When NPs are spin-coated on the micropillars, LSPs create an additional recombination channel with a very high density of photonic states, competing with nonradiative recombination channels and effectively increasing the IQE, thereby reducing the PL decay lifetime.²⁹

It is noteworthy that MP-Ag exhibits the shortest PL decay lifetime, because without the SiO_2 insulating layer, the distance between Ag NPs and QWs is smaller. Since the coupling efficiency of LSP with QWs strongly depends on their distance, the coupling efficiency between Ag NPs and QWs is higher compared to Ag/SiO₂ NPs, resulting in a shorter PL decay lifetime. However, during the coupling process between Ag NPs and QWs, a large number of electrons tunnel from QWs to Ag, causing only a portion of the electrons generated by LSPR to enhance carrier radiative recombination and light output, while the rest are converted to nonradiative losses rather than enhanced exciton output. This energy loss partially quenches the PL intensity. This explains why MP-Ag has a faster PL decay lifetime but lower PL intensity compared to MP-Ag/SiO₂.

Graphene. Figure 5a is the scanning electron microscope (SEM) images of the MP- μ LED and light-emitting mesa we fabricated. The light-emitting mesa size is 50 μ m \times 50 μ m, and the micropillar area size is 40 μ m \times 40 μ m. It can be seen that the micropillars are uniformly arranged and the gaps between the micropillars are sufficient to accommodate a large number of NPs. To enhance the current spreading of the MP- μ LED, we transferred a monolayer graphene as a transparent conductive layer to connect the individual micropillars. Figure 5b and c show the surface morphology of the micropillars before and after transferring the graphene. Figure 5d shows the transmittance of the monolayer graphene used in this experiment at different wavelengths. In the emission wavelength range of the LED designed in this experiment, the transmittance reaches 96.5%. Figure 5e shows the Raman spectra of the graphene before and after transfer. The ratio of the 2D peak to the G peak and the full width at half-maximum (fwhm) of the 2D peak indicate that this is a monolayer graphene.

The optoelectronic properties before and after transferring the graphene are shown in Figure 5f,g. Without the graphene, the MP- μ LED's micropillar area emits weakly. After trans-



Figure 6. (a) I-V characteristics of the two types of MP- μ LEDs with NPs. Optical performance of MP- μ LEDs without NPs, with Ag NPs, and with Ag/SiO₂ NPs: (b) light output power, (c) luminous efficiency, (e) luminous flux, (d) luminous intensity, and (f) EL spectra at 20 mA.



Figure 7. Comparison of optical performance between MP- μ LEDs with Ag/SiO₂ NPs and plane μ LEDs: (a) luminous flux and light output power, (b) luminous efficiency, (c) WPE and EQE, and (d) EL spectra at 20 mA.

ferring the graphene, the emission becomes more uniform, and the micropillar area can light up normally, significantly improving the light output power. The electroluminescence (EL) intensity of the MP- μ LED after transferring graphene increased by 60% at a current of 20 mA, and the turn-on resistance was also lower. This indicates that using graphene as a transparent conductive layer to connect the micropillars is feasible.

Comparison of Different Devices. We tested the electrical and optical properties of the three types of MP- μ LEDs after transferring graphene. Figure 6a shows the I-V characteristics of the two MP- μ LEDs with nanoparticles. The

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leakage current, which might be due to the short circuit between P-GaN and N-GaN caused by the aggregation of Ag NPs in the micropillar gaps. In contrast, the MP- μ LED with Ag/SiO₂ NPs shows almost no leakage current because the SiO₂ insulating layer prevents this issue, highlighting one of the advantages of Ag/SiO₂ NPs. Figure 6b-f, respectively, show the light output power, luminous efficiency, luminous flux, luminous intensity, and EL spectra at a current of 20 mA for the three types of MP- μ LEDs. The MP- μ LED with Ag/SiO₂ NPs demonstrates the best optical performance, further confirming the effectiveness of using Ag/SiO₂ NPs with an insulating layer to enhance the emission of MP- μ LEDs.

We compared the MP- μ LEDs with Ag/SiO₂ to plane μ LEDs of the same size. Figure 7a shows the comparison of the two devices in terms of luminous flux with the light output power presented as the inset. The comparison of luminous efficacy is shown in Figure 7b. The MP- μ LED-Ag/SiO₂ consistently exhibited superior optical performance. The comparison of WPE and EQE is shown in Figure 7c, where the inset shows the EQE. at a current density of 1000 A/cm², the EQE and WPE increased by 44% and 45%, respectively. Figure 7d shows the EL spectra of the two devices under a driving current of 20 mA (800 A/cm²). The EL intensity of MP- μ LED-Ag/SiO₂ has increased by 17% compared with that of Plane- μ LED. This comparison indicates that the proposed MP-µLEDs with Ag/ SiO₂ NPs have the potential to outperform traditional plane μ LEDs in practical applications, demonstrating superior performance.

DISCUSSION

In this paper, we present a μ LED with a micropillar structure, where the micropillars are connected by a monolayer graphene transparent conductive layer, ensuring excellent current spreading and emission uniformity. Using a spin-coating method, we filled the gaps between the micropillars with Ag NPs and Ag/SiO₂ NPs, whose absorption resonance peaks match the emission wavelength of the μ LED. The micropillar structure allows close contact between the QWs and Ag NPs, enhancing the optical performance of the μ LED through LSPR. To investigate the impact of the SiO₂ insulating layer on the optical performance of MP- μ LEDs, we conducted finite element analysis and device testing. We found that Ag/SiO₂ NPs with an insulating layer significantly improved the optical performance of MP-µLEDs, and thinner SiO₂ layers had a more pronounced effect on enhancing the device's optical performance. Compared to plane μ LEDs, the MP- μ LEDs with graphene transparent electrodes and LSP coupling showed a 44% increase in EQE and a 45% increase in WPE at a current density of 1000 A/cm^2 . We believe this work paves the way for future practical applications of nanostructures and LSP in μ LEDs, demonstrating a significant potential for improved performance.

ASSOCIATED CONTENT

Supporting Information

The Supporting Information is available free of charge at https://pubs.acs.org/doi/10.1021/acsphotonics.4c01514.

> Preparation processes of Ag NPs and Ag/SiO₂ NPs; TEM images of Ag NPs and Ag/SiO₂ NPs with different SiO₂ layer thicknesses; Construction method and results of finite element analysis model for coupling of Ag NPs

and Ag/SiO₂ NPs with QWs; Optical performance comparison of MP-µLED with Ag NPs and Ag/SiO₂ NPs of different SiO₂ layer thicknesses; The crosssectional structure of MP-µLED and the schematic diagram of micropillar; The comparison of the electrical and optical performance of four types of devices: planeµLED, MP-µLED, MP-µLED-Ag, and MP-µLED-Ag/ SiO₂; The comparison of the electrical and optical performance of plane- μ LED and MP- μ LED; The TRPL spectra of the micropillar structures and their corresponding energy conversion efficiency (DOCX)

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Notes

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